

PCN-244123

Product Change Notice

Issue Date: 21-February-2022

Change Description:

NiPdAu pre-plated lead-frame

Parts Affected:

AFBR-2555ARZ

HFBR-2555AFZ

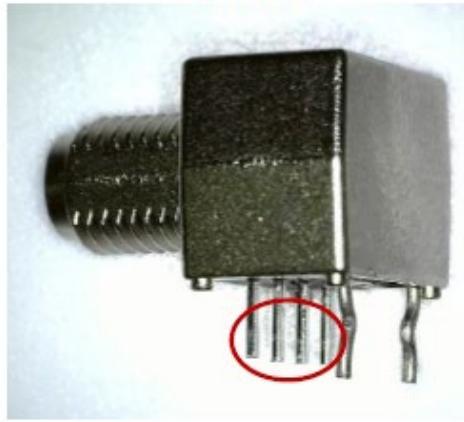
AFBR-1555ARZ

Description and Extent of Change:

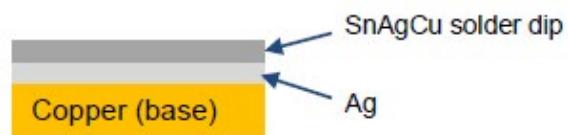
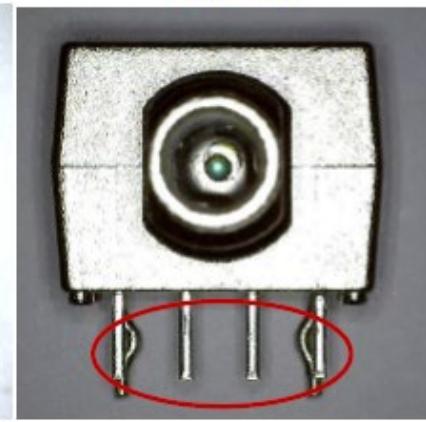
Qualify NiPdAu pre-plated lead-frame to adopt industry standard, improve product reliability, product cycle time and to simplify lead-frame supply chain.

Current

Side View

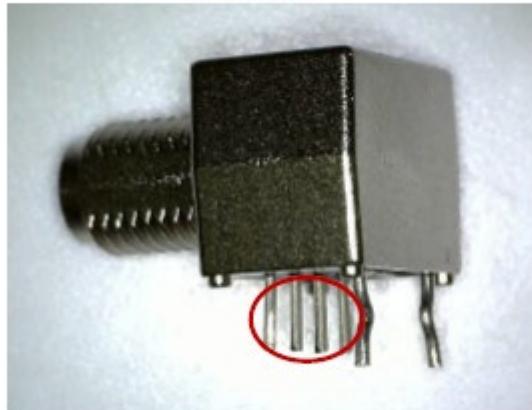


Front View

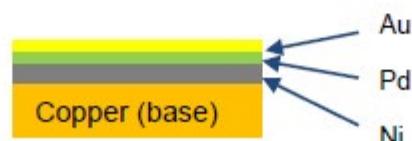
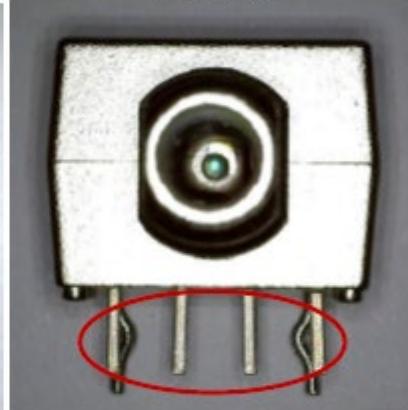


New

Side View



Front View



Active pins (pin5, pin6, pin7 and pin8 in red circle): Affected by changing to new NiPdAu lead-frame finish.

Staple pins or Metal shield mounting pins (pin1, pin2, pin3 and pin4): No Change.

Reasons for Change:

Eliminate additional solder dip process by implementing NiPdAu Pre-plated lead-frame to improve product reliability, product cycle time and to simplify lead-frame supply chain. The NiPdAu pre-plated lead-frame has been qualified and used in other Broadcom industrial products since year 2015. Lead frame layout and base material remain unchanged.

Effect of Change on Fit, Form, Function, Quality, or Reliability:

The product datasheet specification remains the same. Reliability qualifications have been performed to ensure product reliability.

Effective Date of Change:

Product shipments using this change will begin after 05/30/2022. Timing of shipment of the changed part will vary by part number depending on, customer demand, and inventory levels.

Qualification Data:

Qualification Data has been generated and available upon request.

